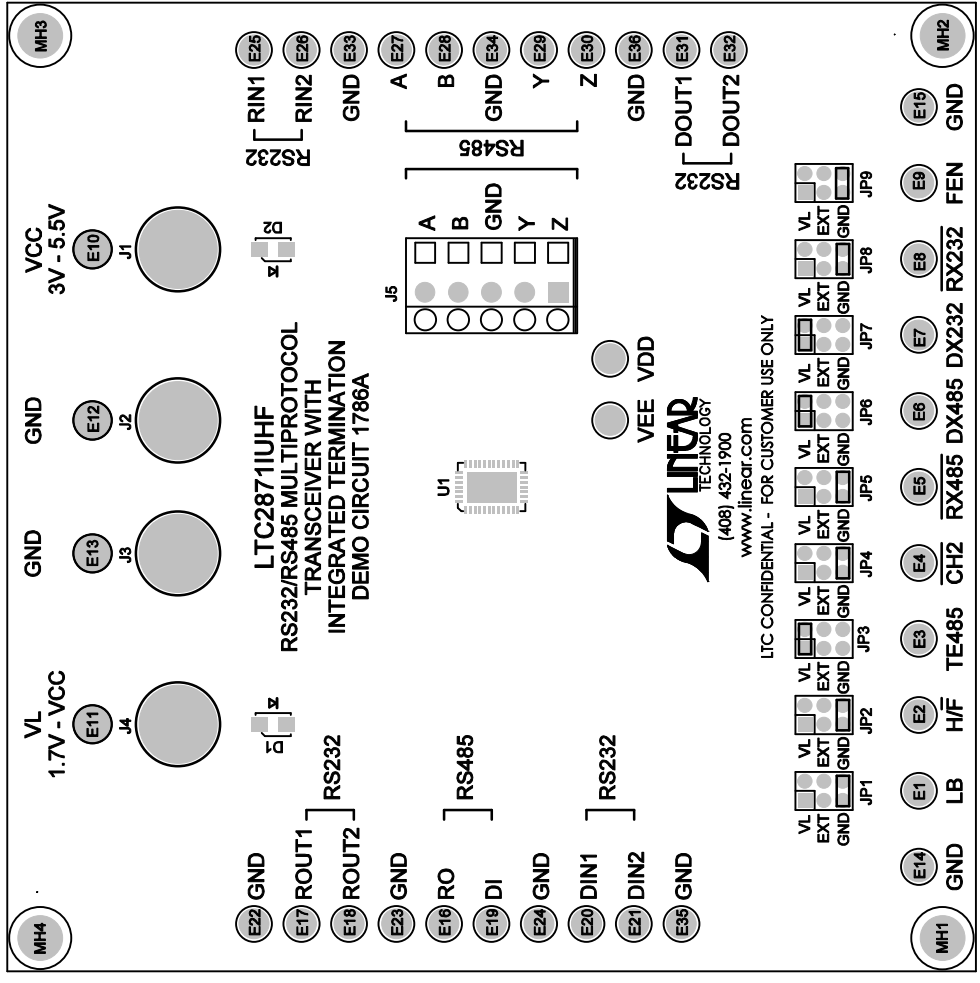
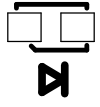


REVISION HISTORY			
ECO	REV	DESCRIPTION	APPROVAL
	1	PRODUCTION	MITCHELL L.
			DATE
			03/30/11

NOTES: UNLESS OTHERWISE SPECIFIED,

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER SMD SIDES. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL 4 STANDOFFS AT 4 LOCATIONS AS SHOWN.
8. INSTALL TURRETS AS SHOWN.
9. INSTALL D1 AND D2 AS SHOWN.



APPROVALS		LTC CONFIDENTIAL - FOR CUSTOMER USE ONLY	
PCB DES.	MI		
APP. ENG.	MITCHELL L.		
SCALE: NONE		TITLE: TOP ASSEMBLY DRAWING, RS232/RS485 MULTIPROTOCOL TRANSCEIVER WITH INTEGRATED TERMINATION	
		SIZE	REV
		N/A	2
		IC NO.	REV
		LTC2871UHF	2
		DEMO CIRCUIT 1786A	
		FILENAME: 1786A-2.PCB	SHT 1 of 2

